

NANOCHEM® Complete Purification Solutions with NANOCHEM® Purifiers





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Complete Purification Solutions with NANOCHEM® Purifiers

Since 1985, MATHESON NANOCHEM® purifiers have provided unprecedented purification solutions to the electronic industry.

NANOCHEM® purifiers were the first point-ofuse purifiers to deliver up to nine 9's purity gas to the semiconductor industry.

Today, NANOCHEM® purifiers offer comprehensive solutions for the source, point-of-use, bulk and proximate purification requirements of specialty gas users.

NANOCHEM® purifiers combine gas-specific purification media and ultra-high purity hardware in one system to eliminate impurities caused by:

- Upstream leaks
- Improper cylinder change-outs
- Increasing impurity concentration during gas cylinder depletion
- Gas system component contamination
- Virtual leaks from component / piping "dead pockets" and soft seats

Oxygen, moisture and other contaminants are removed to < 100 ppt (parts per trillion) and are limited only by the detection limits of even state-of-the-art analytical instrumentation.

Compact and easy to use, NANOCHEM® purifiers can be installed within the gas cabinet or at the process tool. Most purifiers require no heating or cooling and are capable of handling a broad range of flows and pressures.

MATHESON has one of the most extensive, inhouse evaluation laboratories in the industry to assess the quality of gas system components.

The benefit is that components selected for NANOCHEM® purification products are of the highest quality available. "Live gas" testing is done to ensure purifiers meet or exceed performance specifications in the specific process gas for which they are marketed.

NANOCHEM® purifiers offer the highest lifetimes and the best efficiencies for impurity removal. NANOCHEM® purifiers are available for:

- Silicon-source gases
- Nitride gases
- Etchants
- Purge gases
- Dopant gases
- Carrier gases

Purification Performance Benefits & Applications

NANOCHEM® purifiers offer a number of benefits, such as reduced equipment downtime and protection against fluctuations in gas supply quality and upstream system upsets. Typical performance benefits for the semiconductor / compound semiconductor industry are:

- Increased carrier concentration, increased mobility
- Faster crystal growth rates
- Improved uniformity of surface morphology
- Fewer defects in epi layers and substrates
- Longer equipment life & reduced component corrosion

Applications include manufacture of ICs and high brightness LEDs, piping for semiconductor fabs, manufacture of aerospace components, manufacture of process equipment for chemical and biotech industries, and additive manufacturing.



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Purification Media

NANOCHEM® purification media have long been the industry standards for purifying inert gases, such as nitrogen, argon, and sulfur hexafluoride, as well as reactive gases, such as hydrogen, hydrocarbons, and hydride gases (including ammonia, silane, arsine and phosphine).

Gas Type Contaminants **Outlet Purity** Inerts - H_2O < 86 ppt Nitrogen (N₂), Árgon 02 < 50 ppt (Ar), other inerts CO< 100 ppt CO_2 < 24 ppt < 156 ppq Benzene Toluene < 93 ppq Ethylbenzene < 96 ppq < 79 ppq m,p-Xylene o-Xylene < 112 ppq Refractories* < 134 ppq H_2 <1ppb Ammonia H_2O < 45 ppb (NH₃)02 < 0.1 ppb CO₂< 11 ppb Carbamate < 11 ppb GeH₄ <1ppb SiH₄ < 3 ppb Siloxanes < 40 ppb Metals ΑI < 0.6 ppbCu < 0.27 ppb Fe < 0.8 ppb Κ < 0.35 ppb < 0.27 ppb Na Si < 1.3 ppbW < 0.11 ppb Zn < 0.27 ppb Zr < 0.11 ppb

Applications include biotech, chemical processing, aerospace, analytical, petroleum refining, semiconductor / compound semiconductor processes, including low temperature SiGe Epi, SiN and GaN MOCVD processes, and additive manufacturing.

Gas Type	Contaminants	Outlet Purity	
Ammonia	Hydrocarbons from Liquid NH₃		
(NH ₃) - continued	Napthenic and Paraffins	85% removal	
	Ethyl Benzene	96% removal	
	Dissolved other HC	<200 ppb	
	Hydrocarbons from Gaseous NH₃		
	n-Butane	< 30 ppb	
	Ethylbenzene	< 30 ppb	
Carbon Dioxide (Purifier material HCX)	Isopropyl Alcohol	< 200 ppt	
	Acetone	< 93 ppt	
	Propene	<1 ppt	
	Ethanol	< 1 ppt	
	Carbon Disulfide	<1 ppt	
	Hexane	<1 ppt	
	Benzene	<1 ppt	
Carbon Dioxide (Purifier material HCX) continued	Heptane	< 1 ppt	
	Toluene	< 1 ppt	
	m,p-Xylene	< 1 ppt	
	o-Xylene	< 1 ppt	
	Ethyl Toluene	< 1 ppt	
	1,3,5-Trimethyl Benzene	< 1 ppt	
	1,2,4-Trimethyl Benzene	< 1 ppt	
	DichloroBenzene	< 1 ppt	
Silane (SiH4)	H ₂ O	< 100 ppt	
	O ₂	< 100 ppt	
	CO_2	< 100 ppt	
	CO**	< 1 ppb	
	Chlorosilanes, disilane, siloxanes, arsine, phosphine		

Coo Turns	Comtominanto	Outlet Busits
Gas Type	Contaminants	Outlet Purity
Hydrogen (H ₂)	H ₂ O	< 100 ppt
	02	< 100 ppt
	CO ₂	< 100 ppt
Methane (CH ₄)	CO**	< 1 ppb
Ethane (C_2H_6), other HC	NOx, SOx, H2S	
Sulfur	H₂O in inert gas	< 100 ppt
Hexafluoride (SF ₆)	O ₂ in inert gas	< 100 ppt
	CO2 in inert gas	< 100 ppt
Carbon Tetrafluoride (CF ₄)	H ₂ O in sulfur hexafluoride	< 10 ppb
	O ₂ in sulfur hexafluoride	< 10 ppb
Other Fluorocarbons	H ₂ O in sulfur hexafluoride	< 10 ppb
	O ₂ in sulfur hexafluoride	< 10 ppb
Oxygen (O ₂),	H ₂ O	< 10 ppb
Carbon Dioxide (CO ₂),	H ₂ O	< 10 ppb
Nitrous Oxide (N ₂ O)	H ₂ O	< 10 ppb
Carbon Monoxide (CO)	Metal Carbonyls: Fe, Ni	
Corrosives (HCI,	H ₂ O in inert gas	< 1 ppb
HBr, Cl ₂ , SiH ₂ Cl ₂ , SiHCl ₃ , BCl ₃)	H ₂ O in HBr	< 100 ppb
On 1010/ D010/	H ₂ O in HCl	< 100 ppb
	Volatile Metals***	
	Mo	< 4 ppb
	Ti	< 13 ppb
	Fe(CO)5	< 50 ppb
	. 5(55)5	

Impurity removal depends on purifier material and incoming gas specification

Al, Ca, Cr, Fe, Mg, Ni, K, Na, Zn

Metals removal as demonstrated by intrinsic resistivity measurements on wafer grown by TCS:

- Without MTX Purifier: <200 ohm-cm
- With MTX Purifier: > 2500 ohm-cm and total metals on water <1E10 atoms/cm₂

^{*}Refractories as TMDSO (Tetramethyldisiloxane)

^{**}CO is removed efficiently by OMX & OMX-PlusTM media at low flow rates (recommend 1/10 of normal flow rate)

^{***}Metals removed as measured on wafer via VPD-ICPMS:

Purification Applications - Where to Use Purification

Distribution Line Gas cabinet Process tool Purge gas purification ensures that cylinder changes do not contaminate the process lines and Purifier that the purest purge gas is used. Process Gas Cylinder Pure Gas Cylinder Source gas purification of corrosive gases ensures that cylinder moisture does not corrode the purge manifold, distribution or process lines. 3 Proximate gas purification allows economical purification with a single source purifier for multitool applications. 4 Point-of-connection gas purification ensures process gas consistency for larger flow applications. Point-of-use gas purification eliminates virtually all variables of contamination including gas jungle variables. Typical location would be directly before the chamber or mass flow controller. Bulk gas purification offers economical purification to a central area or entire facility. **Bulk Gas Tanks** FAB Replacement purifiers for replacement of other 7 brand purifiers, previously installed.*

^{*} Drop-In Replacement with identical dimensions

Purification Applications - Where to Use Purification

POINT-OF-USE Purification



PuriFilter®

- Up to 3 slpm (0.18 NM₃/hr)
- 1000 psig (7 MPa) rating
- Poppet valves limit exposure to atmosphere during purifier installation
- Poppet valves limit exposure to residual process gas during purifier replacement



L-Series

- Up to 150 slpm (9 NM₃/hr)
- Inlet / outlet valves
- Optional 3-valve Bypass
- Optional electronic end-point detection
- 150 psig (1.1 MPa) with end-point
- 500 psig (3.5 MPa) without end-point



White Knight Series™

- Competitor Drop-In Replacement Design
- Up to 1000 slpm (60 NM₃/hr)
- Up to 500 psig (3.5 MPa)
- Optional poppet valves
- Optional inlet & outlet valves
- Optional bypass assembly



H-Series

- Ultra-clean construction
- Built-in 1-valve bypass
- Up to 50 slpm (3 NM₃/hr) with H-Series
- Optional electronic endpoint detection
- 150 psig (1.1 MPa) with end-point
- 500 psig (3.5 MPa) without end-point



A-Series

- For 100% arsine & phosphine service
- For use in ASM & MATHESON SideCar™ custom purification cabinet
- Optional electronic endpoint detection
- Up to 20 slpm (1.2 NM₃/hr) in AsH₃/PH₃ service
- Up to 60 psig (0.4 MPa) in AsH₃/PH₃ service
- Up to 150 slpm (9 NM₃/hr) in inert gas service
- Up to 500 psig (3.5 MPa) in inert gas service
- Competitor Drop-In Replacement Design

HIGH PRESSURE Purification (Source)



HP-Series

- For installation after cylinder CGA connection
- Reduce manifold corrosion with corrosive gases
- Up to 2,850 psig (19.7 MPa)
- Flow rates up to 50 slpm (3 NM₃/hr)
- Built-in 1-Valve Bypass



MAX^{TM}

- High capacity, high flow, and high pressure
- 10L volume
- Up to 5000 slpm (180 m₃/h) and 3000 psig (207 bar)
- Sub-ppt efficiency

HIGH TECHNOLOGY WELDING Purification



WeldAssure™ Series

- Up to 50 slpm (100 cfh, 3 NM₃/hr))
- Up to 200 psig (1.5 MPa)
- Built-in 1-valve (4-Way valve) bypass
- Check valve at outlet to protect canister media from air intrusion when gas flow is stopped
- Visual end-point detection
- Field-replaceable canister
- Inexpensive Brass components & disposable aluminum canister
- Optional refillable stainless canister
- Optional stainless components with stainless canister



Weld Knight™ Series

- Up to 250 slpm (530 cfh, 15 NM₃/hr)
- Up to 200 psig (1.5 MPa)
- Built-in 1-valve (4-Way valve) bypass
- Check valve at outlet to protect canister media from air intrusion when gas flow is stopped
- Field-replaceable canister
- Refillable stainless steel canister
- Stainless valves and fittings

BULK Purification



Megashield™ (MS-Series)

- Up to 1000 slpm (60 NM₃/hr)
- Up to 150 psig (1.1 MPa) with end-point
- Up to 350 psig (2.5 MPa) without end-point
- Optional bypass manifold

CUSTOM Purification



SideCar™

- Custom cabinet with A-Series H₂, N₂ and HCl purifiers
- Designed for ASM America Epsilon and Polygon tools
- Can be used as stand-alone cabinet
- Optional NanoShield process protection system
- Up to 100 psig (0.7 MPa)
- H_2 and N_2 : Up to 150 slpm (9NM₃/hr)
- HCI: Up to 50 slpm (3 NM₃/hr)



Pico-Trap™

- Acetone removed to 500 ppm ±100 ppm
- C₂H₂ cylinder pressure ranges between 280 psig and 50 psig
- C₂H₂ flow up to 14 slpm
- Operating Pressure ±1 psig
- Operating Temperature ±1°C

ADDITIVE MANUFACTURING Purification



3DPro™

- 57 liter purifier
- Removal of water only or removal of water and oxygen to less than 1 ppb
- Temperature probe and readout is available to monitor the internal temperature of purifier bed
- High flow ball valves and gate valve used for lowest pressure drop
- Flow rates up to 5000 slpm depending on customermaximum allowable pressure drop

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- Maximum operating pressure is 125 psig
- Maximum operating temperature is 40°C



